

Using the TPS56221EVM-579

User's Guide



Literature Number: SLVU446A
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4.5-V to 14-V Input High-Current Synchronous Buck Converter

1 Introduction

The TPS56221EVM-579 evaluation module (EVM) is a synchronous buck converter providing a fixed 1.0-V output at up to 25 A from a 12-V input bus. The EVM is designed to start up from a single supply; so, no additional bias voltage is required for start up. The module uses the TPS56221 High-Current Synchronous Buck Converter with integrated MOSFETs.

The TPS56221 integrates TI's high performance controller technology with TI's industry leading MOSFET technology in a standard QFN package to meet the demands of modern, high-current, and space constrained applications.

2 Description

TPS56221EVM-579 is designed to use a regulated 12-V (8-V to 14-V) bus voltage to provide a regulated 1.0-V output at up to 25 A of load current. TPS56221EVM-579 is designed to demonstrate the TPS56221 high-current integrated FET converter in a typical space-limited, 12-V bus to low-voltage point-of-load application.

2.1 Applications

- High-Current, Low-Voltage FPGA or Micro Controller Core Supplies
- High-Current Point-of-Load Modules
- Telecommunications Equipment
- Computer Peripherals

2.2 Features

- 8-V to 14-V Input Voltage Rating
- 1.0-V $\pm 2\%$ Output Voltage Rating
- 25-A Steady-State Load Current
- 500-kHz Switching Frequency
- Simple Access to Power Good, Enable/Soft-Start and Error Amplifier
- Convenient Converter Performance Test Points

3 Electrical Performance Specifications

Table 1. TPS56221EVM-579 Electrical Performance Specifications

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input Characteristics						
V_{IN}	Input voltage		8	12	14	V
I_{IN}	Input current	VIN = 12 V, IOUT = 25 A		2.42		A
	No load input current	VIN = 12 V, IOUT = 0 A		43		mA
V_{IN_UVLO}	Input UVLO	IOUT = 25 A		4.2		V
Output Characteristic						
V_{OUT}	Output voltage	VIN = 8 V to 14 V, IOUT = 0 A to 25 A	0.98	1.0	1.02	V
	Line regulation	VIN = 8 V to 14 V, IOUT = 25 A		0.1%		
	Load regulation	VIN = 12 V, IOUT = 0 A to 25 A		1%		
V_{RIPPLE}	Output voltage ripple	VIN = 12 V, IOUT = 25 A		20		mV _{pp}
I_{OUT}	Output current	VIN = 8 V to 14 V	0		25	A
Systems Characteristics						
f_{SW}	Switching frequency		450	500	550	kHz
η_{pk}	Peak efficiency	VIN = 12 V, IOUT = 13 A		89.6%		
η	Full-load efficiency	VIN = 12 V, IOUT = 25 A		87.1%		
	Operating temperature			25		°C

4 Schematic

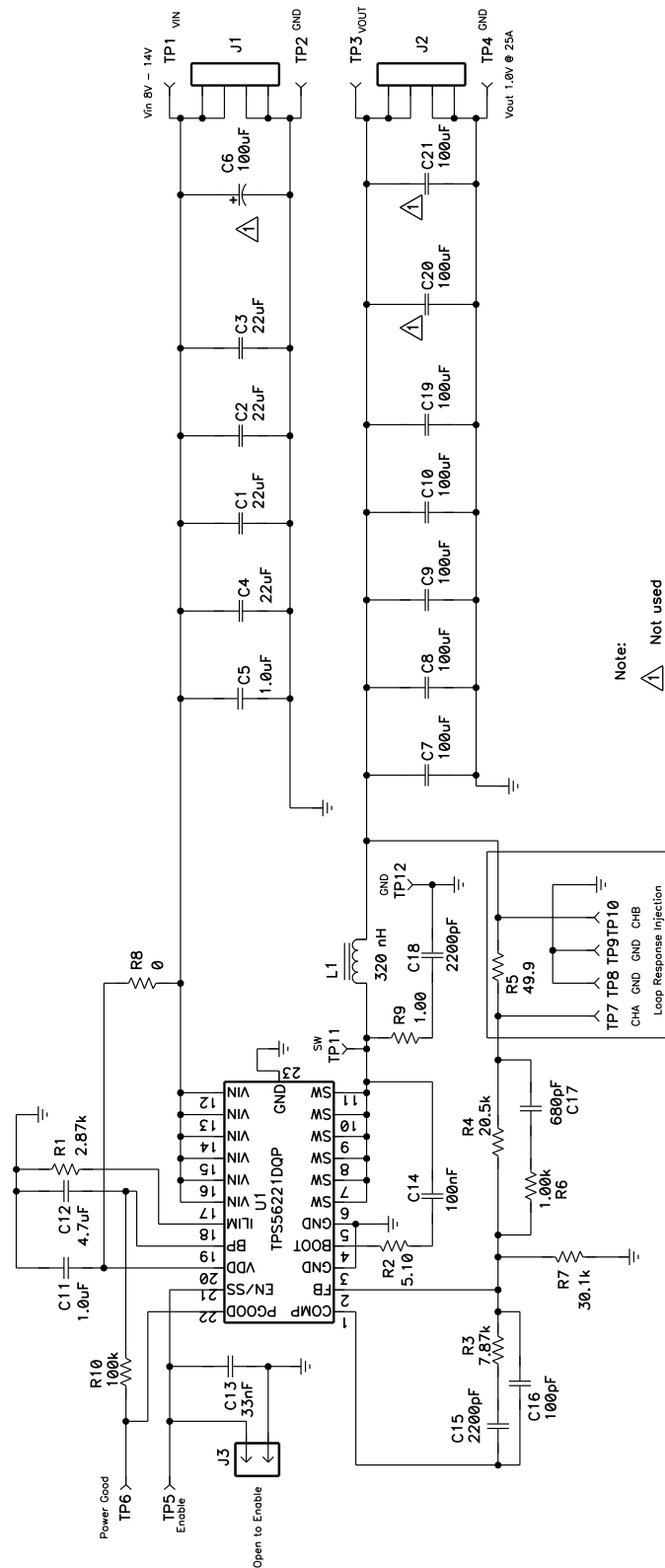


Figure 1. TPS56221EVM-579 Schematic

5 Test Setup

5.1 Test Equipment

5.1.1 Voltage Source

VIN: The input voltage source (VIN) shall be a 0-V to 15-V variable DC source capable of supplying 4 A_{DC}.

5.1.2 Meters

- **A1:** Input current meter (0 A_{DC} to 4 A_{DC}).
- **V1:** Input voltage meter (0 V to 15 V).
- **V2:** Output voltage meter (0 V to 2 V).

5.1.3 Load

LOAD: Output load. Electronic load set for constant current or constant resistance mode, capable of 0 A_{DC} to 25 A_{DC} at 1.0 V_{DC}.

5.1.4 Oscilloscope

For Output Voltage Ripple: Oscilloscope shall be an analog or digital oscilloscope set for AC coupled measurement with 20-MHz bandwidth limiting. Use 20-mV/div vertical resolution, 1.0-μs/div horizontal resolution.

For Switching Waveforms: Oscilloscope shall be an analog or digital Oscilloscope set for DC coupled measurement with 20-MHz bandwidth limiting. Use 2-V/div or 5-V/div vertical resolution and 1.0-μs/division horizontal resolution.

5.1.5 Fan

The TPS56221EVM-579 Evaluation Module includes components that can get hot to touch when operating. Because this evaluation module is not enclosed to allow probing of circuit nodes, a small fan capable of 200 lfm to 400 lfm is recommended to reduce component temperatures when operating.

5.2 Recommended Wire Gauge

5.2.1 VIN to J1

The connection between the source voltage (VIN) and J1 of TPS56221EVM-579 can carry as much as 4 A_{DC} of current. The minimum recommended wire size is AWG #16 with the total length of wire less than 2 feet (1 foot input, 1 foot return)

5.2.2 J2 to LOAD

The connection between the LOAD and J2 of TPS56221EVM-579 can carry as much as 25 A_{DC} of current. The minimum recommended wire size is 2xAWG #14 with the total length of wire less than 2 feet (1 foot input, 1 foot return).

NOTE: J2 is a 4 position terminal jack using positions for each V_{OUT} and GND. Each position is rated to support 15 A of output current. When delivering more than 15 A of current, both V_{OUT} and both GND positions should be used.

5.3 Equipment Set Up Procedure

Figure 2 is the recommended test setup to evaluate the TPS56221EVM-579.

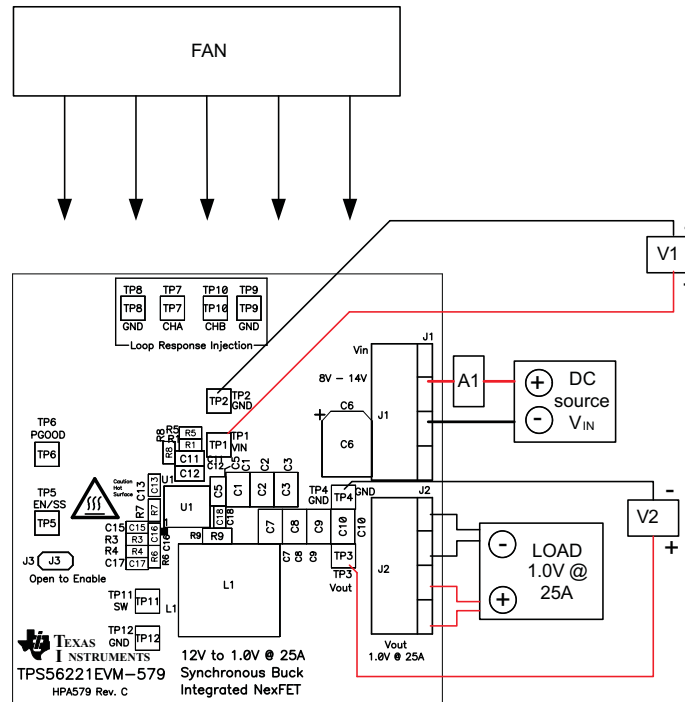


Figure 2. TPS56221EVM-579 Recommended Test Setup

1. Working at an ESD workstation, make sure that any wrist straps, bootstraps and mats are connected referencing the user to earth ground before power is applied to the EVM. Wearing electrostatic smock and safety glasses is also recommended.
2. Prior to connecting the DC input source, VIN, it is advisable to limit the source current from VIN to 4.0 A maximum. Make sure VIN is initially set to 0 V and connected as shown in Figure 2.
3. Connect VIN to J1 as shown in Figure 2.
4. Connect ammeter A1 between VIN and J1 as shown in Figure 2.
5. Connect voltmeter V1 to TP1 and TP2 as shown in Figure 2.
6. Connect voltmeter V2 to TP3 and TP4 as shown in Figure 2.
7. Place the fan as shown in Figure 2 and turn it on, ensuring that the air blows directly across the evaluation module.

6 Configurations

6.1 Enable Selection (J3)

The converter can be enabled and disabled by J3. Shorting J3 discharges the soft-start capacitor and disables the TPS56221 converter. Opening J3 enables the TPS56221 converter.

Default setting: short to disable the converter.

7 Test Point Descriptions

Table 2. Test Point Descriptions

TEST POINT	LABEL	DESCRIPTION
TP1	VIN	Measurement test point for input voltage
TP2	GND	Ground test point for input voltage
TP3	VOUT	Measurement test point for output voltage
TP4	GND	Ground test point for output voltage
TP5	EN/SS	Measurement test point for enable/soft-start
TP6	PGOOD	Measurement test point for power good
TP7	CHA	Measurement test point for channel A of loop response
TP8	SGND	Ground test point for channel A of loop response
TP9	SGND	Ground test point for channel B of loop response
TP10	CHB	Measurement test point for channel B of loop response
TP11	SW	Measurement test point for switch node voltage
TP12	GND	Ground test point for switch node voltage

7.1 Input Voltage Monitoring (TP1 and TP2)

TPS56221EVM-579 provides two test points for measuring the input voltage applied to the module. This allows the user to measure the actual input module voltage without losses from input cables and connectors. To use TP1 and TP2, connect a voltmeter positive input terminal to TP1 and negative input terminal to TP2.

7.2 Output Voltage Monitoring (TP3 and TP4)

TPS56221EVM-579 provides two test points for measuring the output voltage generated by the module. To use TP3 and TP4, connect a voltmeter positive input terminal to TP3 and negative input terminal to TP4. For output ripple monitoring, please refer to the tip and barrel measurement technique in [Section 8.2](#).

7.3 Enable/Soft-start Monitoring (TP5)

TPS56221EVM-579 provides a test point for measuring the enable/soft-start voltage of the TPS56221 converter. This test point can be monitored to observe the start-up calibration waveform, soft-start ramp or fault time-out timing.

The enable/soft-start test point should not be actively driven from an external circuit, such as a logic output of another power supply.

7.4 Power Good Monitoring (TP6)

TPS56221EVM-579 provides a test points for measuring the Power Good voltage of the TPS56221 converter.

7.5 Loop Response Testing (TP7, TP8, TP9 and TP10)

TPS56221EVM-579 provides four test points (two signals and two grounds) for measuring the control loop frequency response. This allows the user to measure the actual module loop response without modifying the evaluation board. See [Section 8.3](#) for additional detail.

7.6 Switch Node Voltage Monitoring (TP11 and TP12)

TPS56221EVM-579 provides two test points for measuring the switch node. To monitor the switch node voltage, set oscilloscope per Oscilloscope For Switching Waveforms in [Section 5.1.4](#). Connect the oscilloscope probe to TP11 and the ground lead of the probe to TP12. To monitor the voltage spike on switch node, please remove the bandwidth limit on the oscilloscope and refer to the Application Report SLPA005 (Reducing Ringing Through PCB Layout Techniques) for the measurement techniques.

8 Test Procedures

8.1 Start Up/Shut Down Procedure

1. Set up the EVM as described in [Section 5.3](#) and [Figure 2](#).
2. Ensure LOAD is set to sink 0 A_{DC}.
3. Ensure jumper J3 set per [Section 6.1](#).
4. Increase VIN from 0 V_{DC} to 12 V_{DC}. Using V1 to measure VIN voltage.
5. Open jumper J3 to enable the converter.
6. Use V2 to measure VOUT voltage, A1 to measure VIN voltage.
7. Vary LOAD from 0 A_{DC} to 25 A_{DC}, VOUT should remain in load regulation.
8. Vary VIN from 8 V to 14 V, VOUT should remain in line regulation.
9. Short jumper J3 to disable the converter.
10. Decrease VIN to 0 V.
11. Decrease LOAD to 0 A.

8.2 Output Ripple Voltage Measurement Procedure

1. Follow [Section 8.1](#) to set VIN and LOAD to desired operating condition.
2. Set oscilloscope for Output Voltage Ripple Measurement in [Section 5.1.4](#).
3. Connect oscilloscope probe with exposed metal barrel to TP3 and TP4 per [Figure 3](#). Using a leaded ground connection may induce additional noise due to the large ground loop.
4. Follow [Section 8.1](#) to power down.

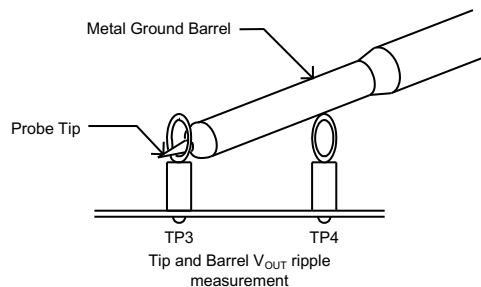


Figure 3. Tip and Barrel Output Voltage Ripple Measurement

8.3 Control Loop Gain and Phase Measurement Procedure

1. Follow [Section 8.1](#) to set VIN and LOAD to desired operating condition.
2. Connect isolation transformer to test points TP7 and TP10 as shown in [Figure 4](#).
3. Connect input signal amplitude measurement probe (Channel A) to TP7 as shown in [Figure 4](#).
4. Connect output signal amplitude measurement probe (Channel B) to TP10 as shown in [Figure 4](#).
5. Connect ground lead of Channel A and Channel B to TP8 and TP9 as shown in [Figure 4](#), respectively.
6. Inject 10 mV or less signal through the isolation transformer.
7. Sweep the frequency from 500 Hz to 500 kHz with 10-Hz or lower post filter.

8. Control loop gain can be measured by
$$20 \times \log \left(\frac{\text{Channel B}}{\text{Channel A}} \right)$$
.
9. Control loop phase can be measured by the phase difference between Channel A and Channel B.
10. Follow [Section 8.1](#) to power down.

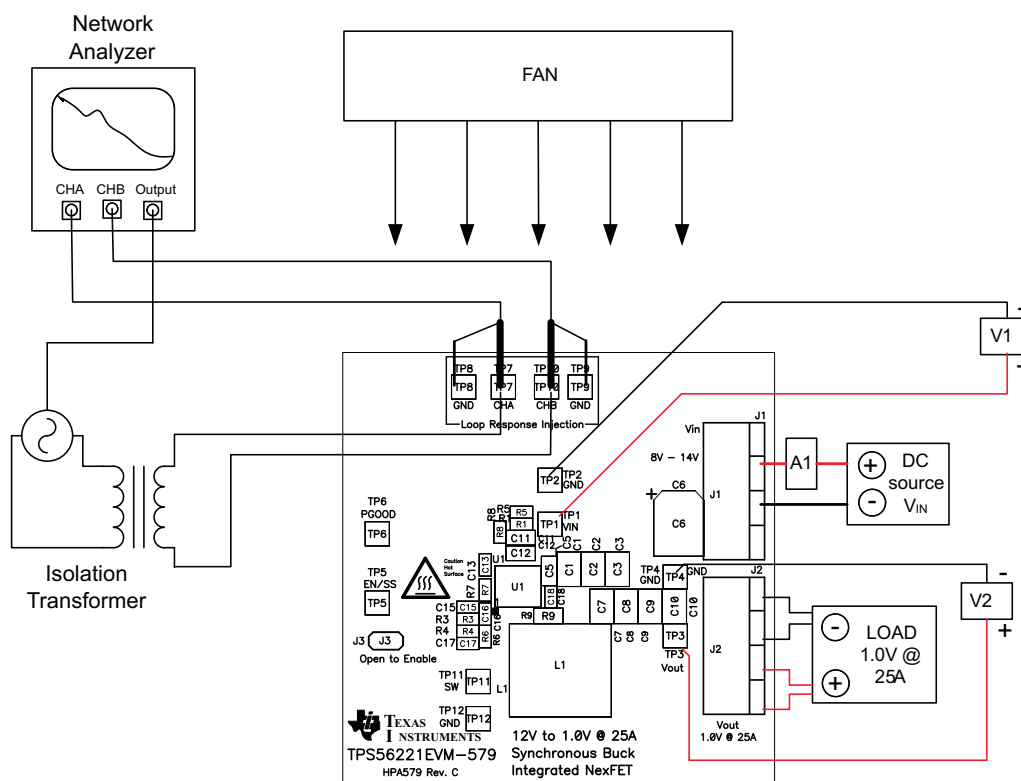


Figure 4. Control Loop Measurement Setup

8.4 Equipment Shutdown

1. Shut down VIN.
2. Shut down LOAD.
3. Shut down fan.
4. Shut down oscilloscope.

9 Performance Data and Typical Characteristic Curves

Figure 5 through Figure 16 present typical performance curves for the TPS56221EVM-579. Since actual performance data can be affected by measurement techniques and environmental variables, these curves are presented for reference and may differ from actual field measurements.

9.1 Efficiency

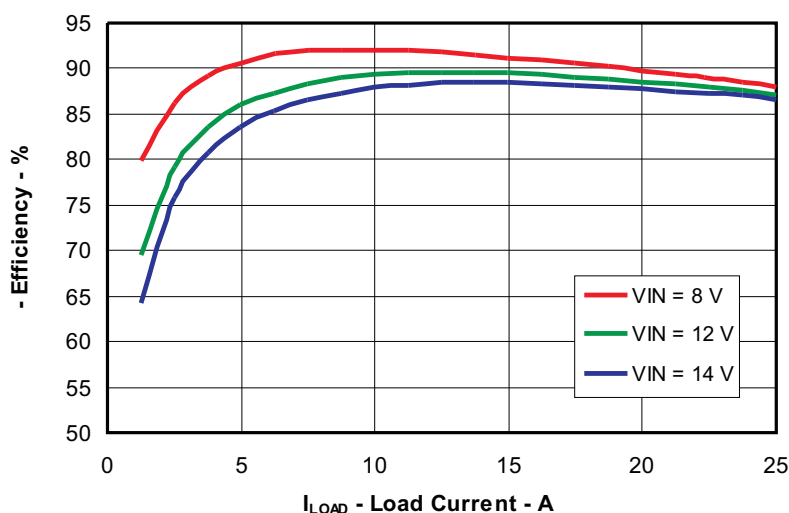


Figure 5. Efficiency

9.2 Load Regulation

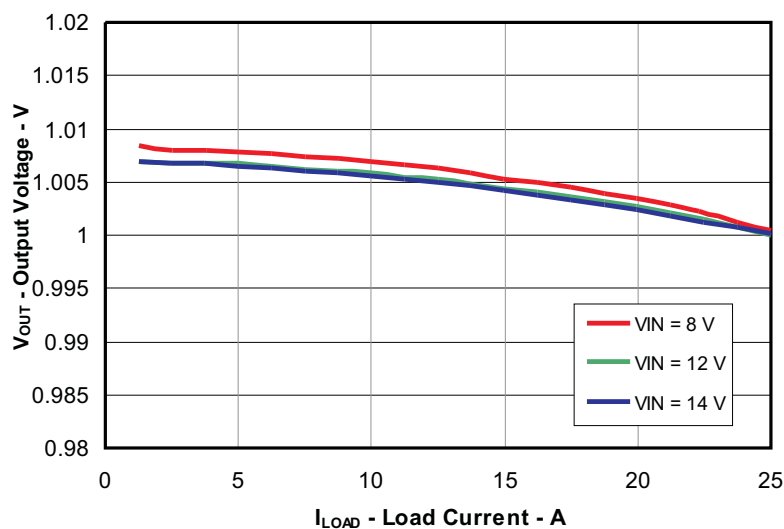


Figure 6. Load Regulation

9.3 Line Regulation

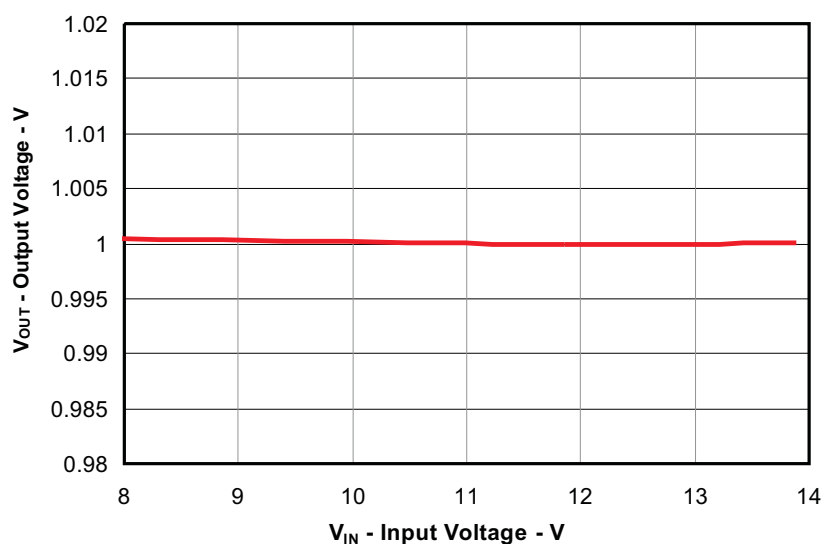


Figure 7. Line Regulation
(V_{IN} = 8 V to 14 V, V_{OUT} = 1.0 V, I_{OUT} = 25 A)

9.4 Output Voltage Ripple

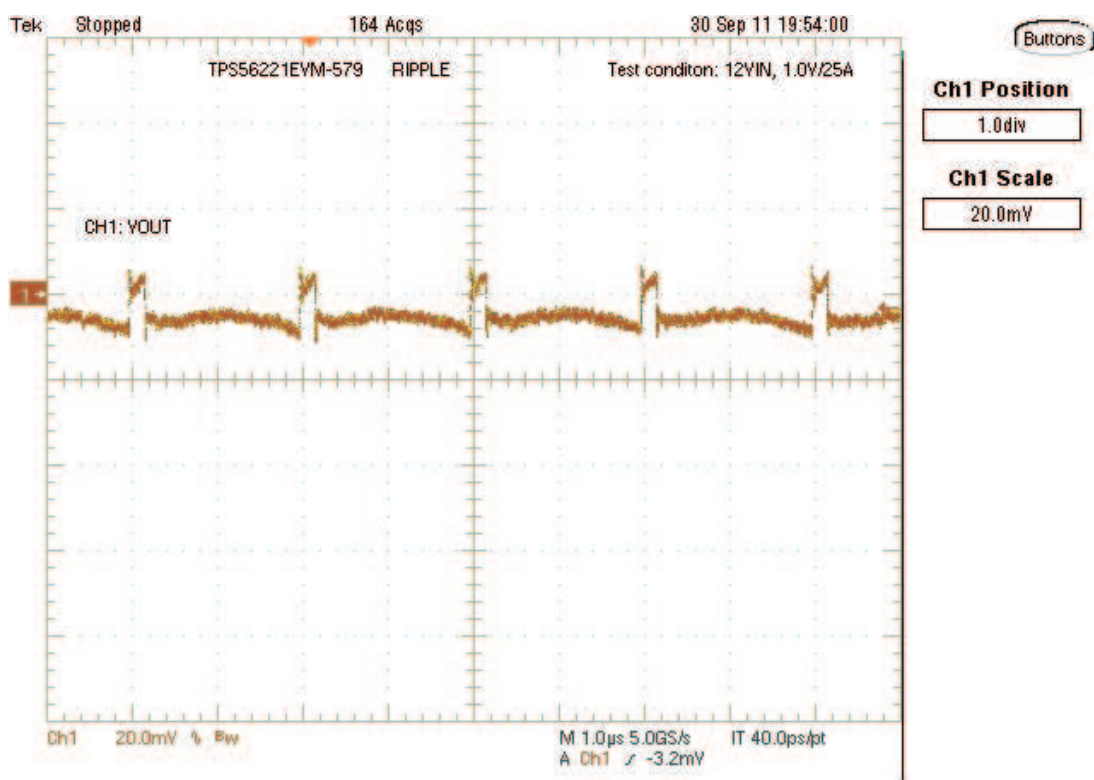
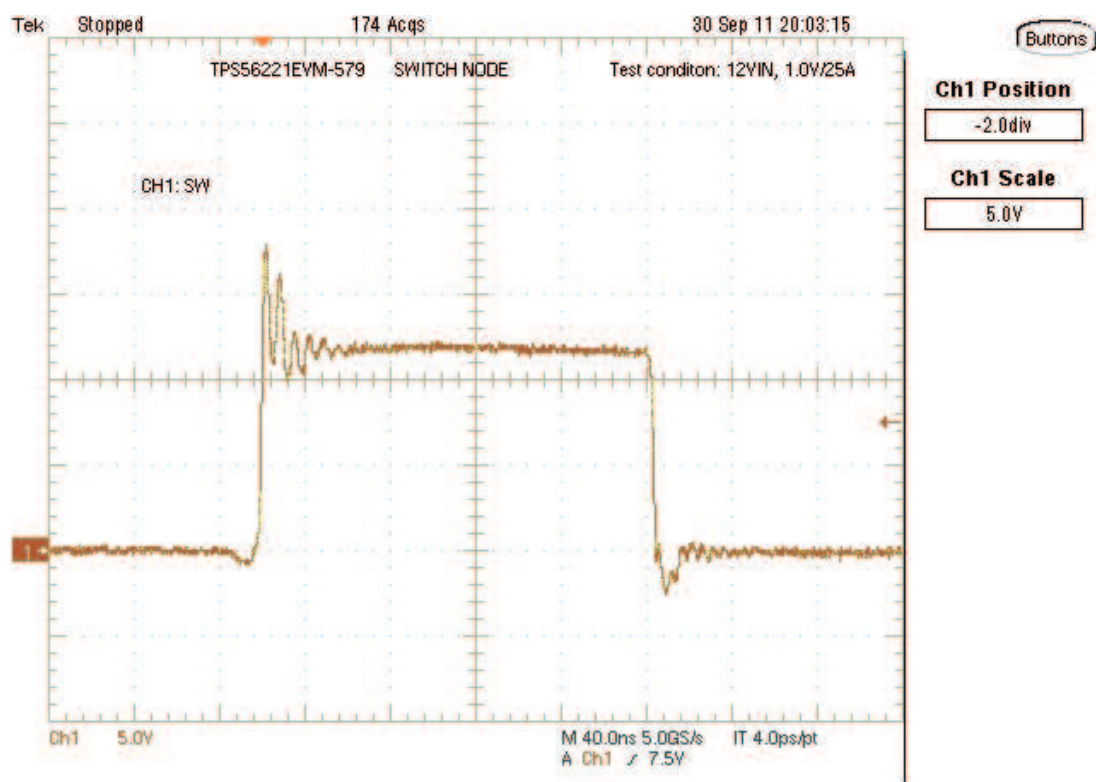


Figure 8. Output Voltage Ripple
(V_{IN} = 12 V, V_{OUT} = 1.0 V, I_{OUT} = 25 A)

9.5 Switch Node



**Figure 9. Switch Node Waveform Measured at Pins Using Tip and Barrel Measurement Technique
(VIN = 12 V, VOUT = 1.0 V, IOUT = 25 A)**

9.6 Load Transient

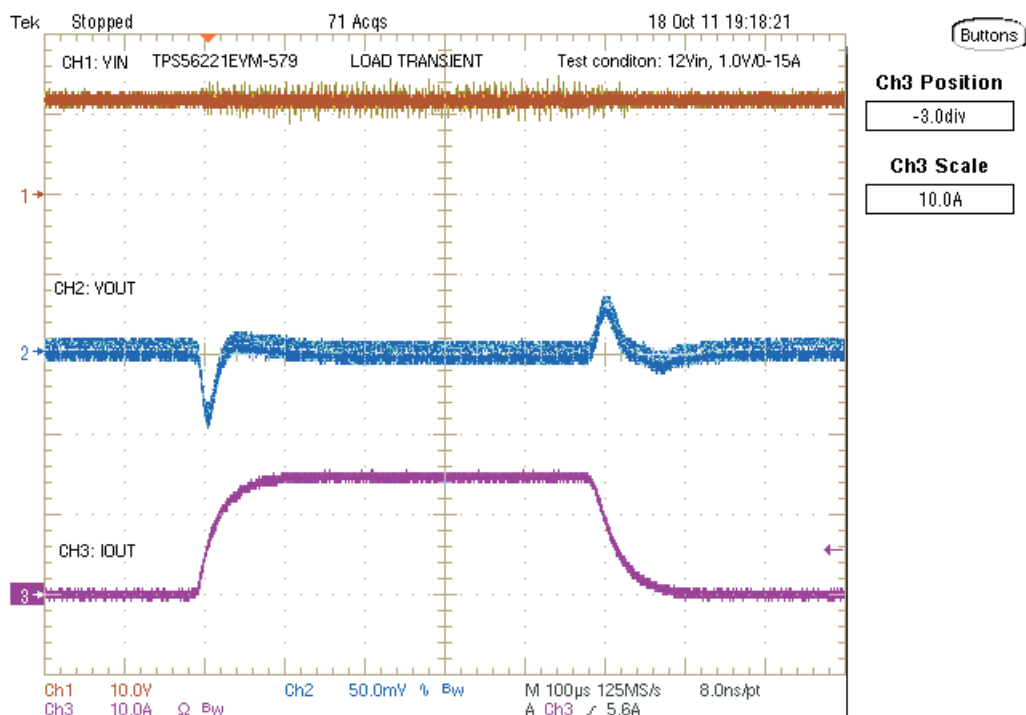


Figure 10. Load Transient
(VIN = 12 V, VOUT = 1.0 V, IOUT = 0 A to 25 A)

9.7 Start Up

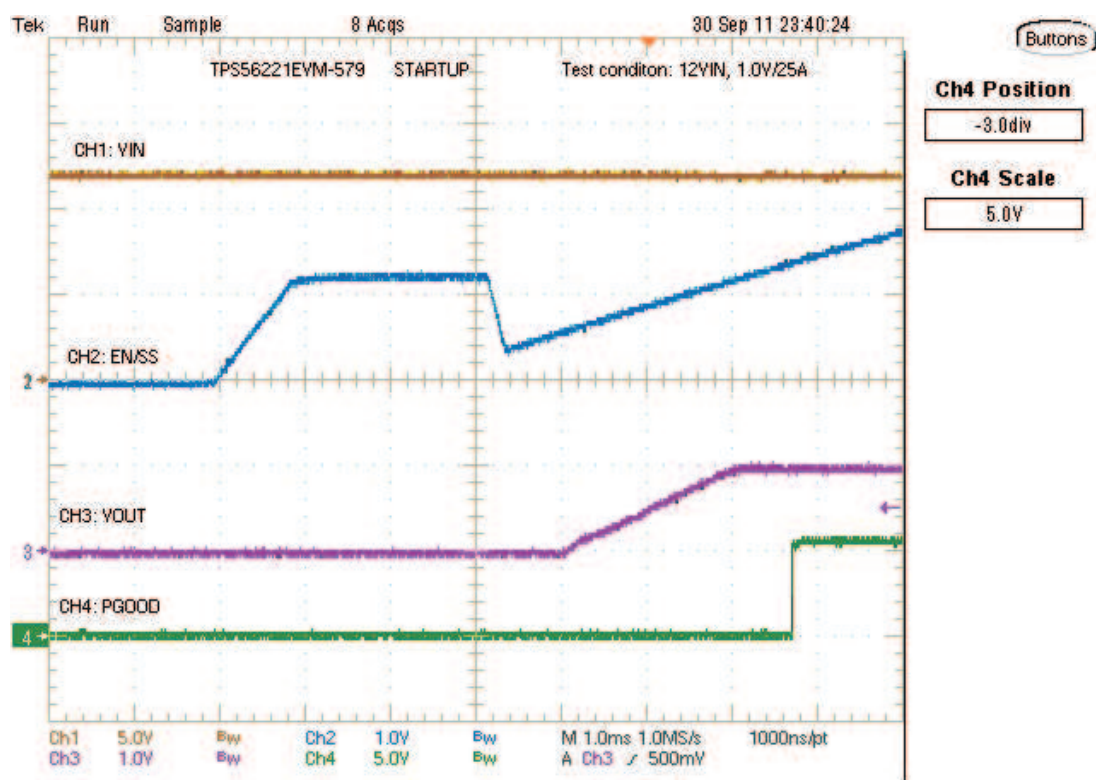


Figure 11. Start-Up Waveform
(VIN = 12 V, VOUT = 1.0 V, IOUT = 25 A)

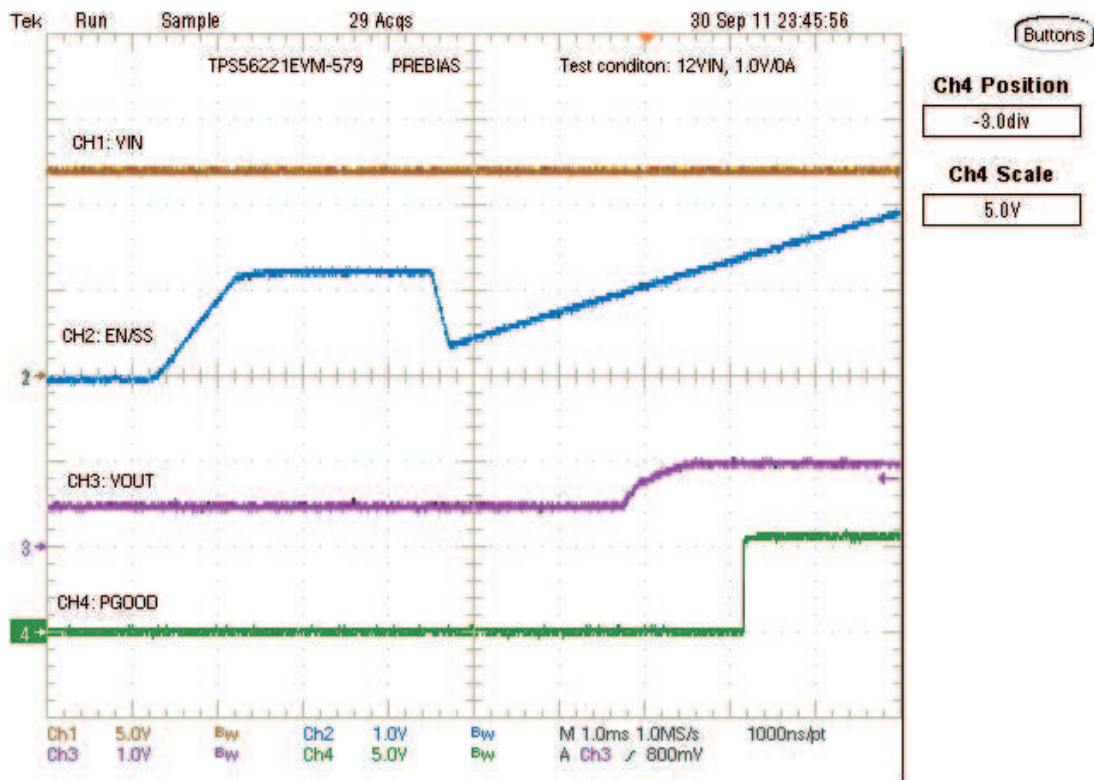


Figure 12. Pre-Biased Start-Up Waveform
(VIN = 12 V, VOUT = 1.0 V, IOUT = 0 A)

9.8 Power Off

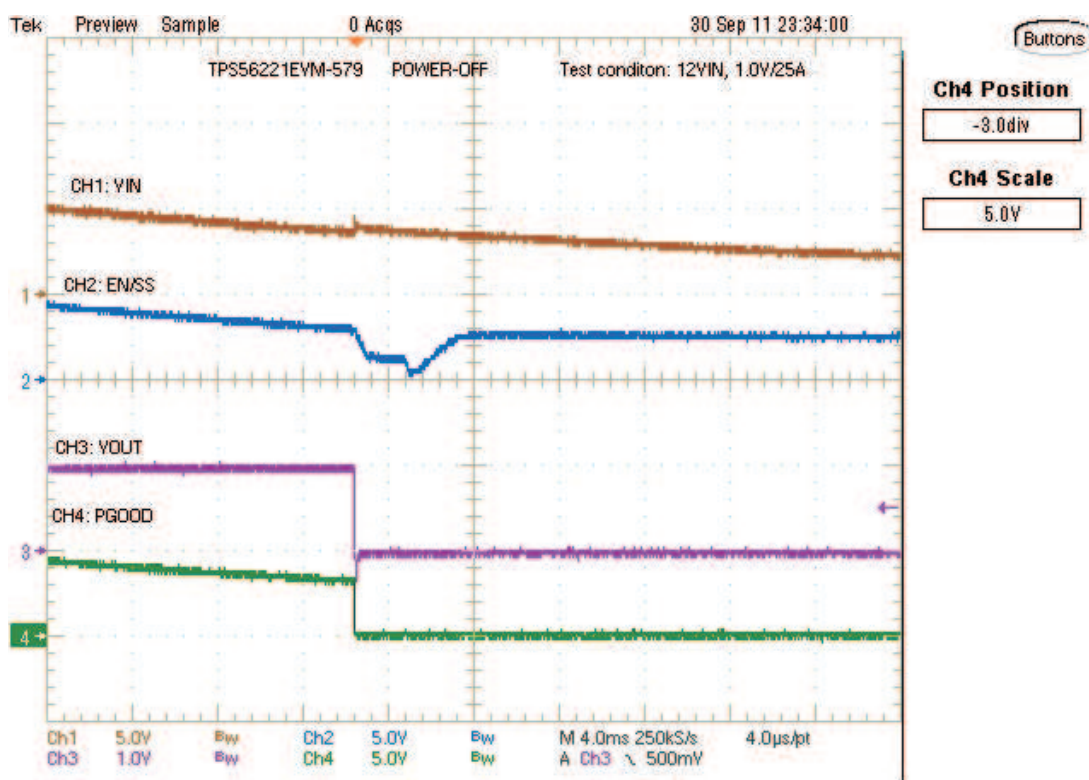


Figure 13. Power-Off Waveform
(VIN = 12 V, VOUT = 1.0 V, IOUT = 25 A)

9.9 Over-Current Protection

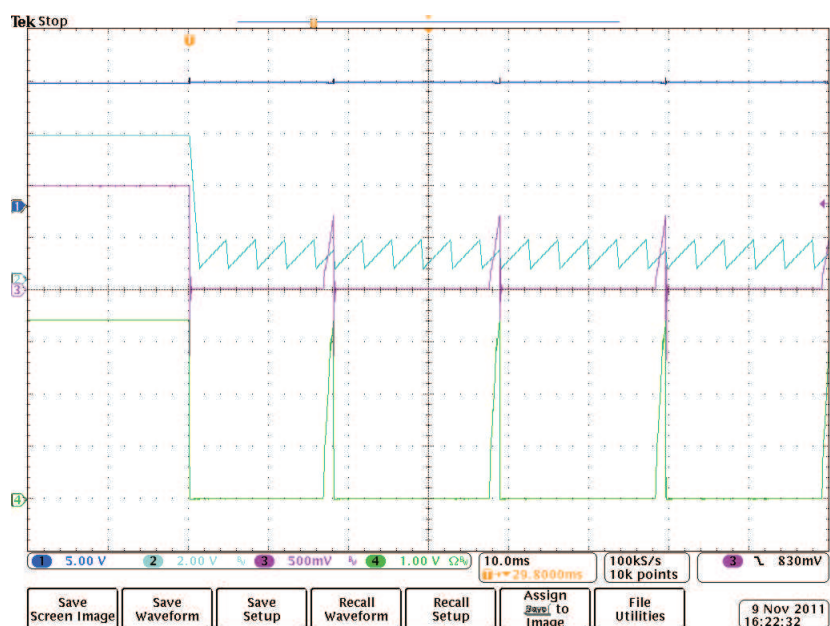


Figure 14. Over-Current Protection Waveform
(Ch1: VIN, Ch2: EN/SS, Ch3: VOUT, Ch4: IOUT (10 A/div), VIN = 12 V, VOUT = 1.0 V, IOUT = 36 A)

9.10 Control Loop Bode Plot

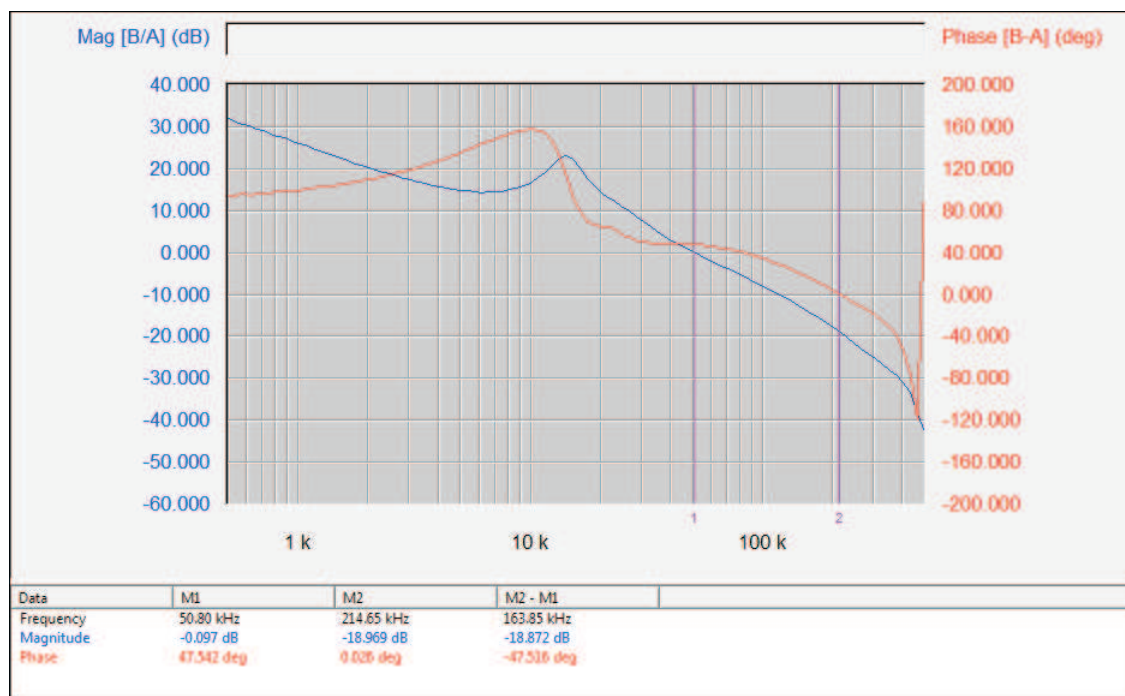


Figure 15. Loop Gain
(VIN = 12 V, VOUT = 1.0 V, IOUT = 25 A, Bandwidth: 51 kHz, Phase Margin: 48°)

9.11 Thermal Image

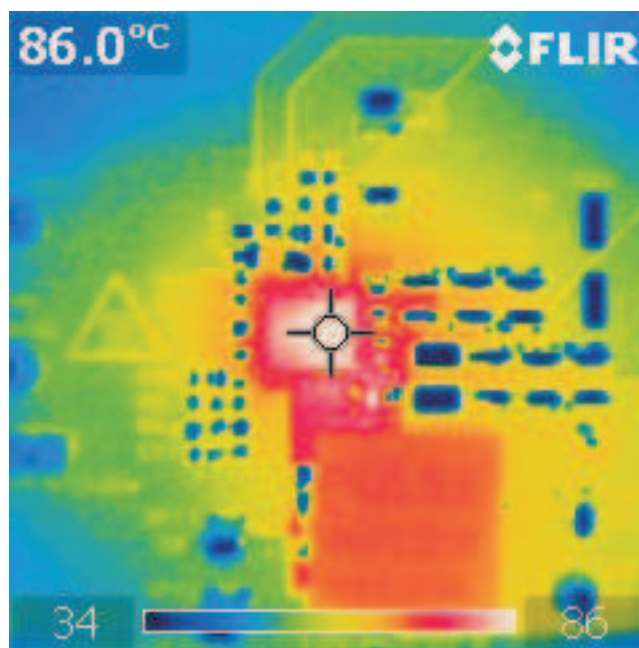


Figure 16. Thermal Image
(VIN = 14 V, VOUT = 1.0 V, IOUT = 25 A, without airflow)

10 EVM Assembly Drawings and PCB Layout

The following figures (Figure 17 through Figure 22) show the design of the TPS56221EVM-579 printed circuit board. The EVM has been designed using a 4-layer, 2-oz copper-clad circuit board 2.5" x 2.5" with components on both sides of the PCB to allow the user to view, probe and evaluate the TPS56221 high current converter with integrated FETs in a small form factor, high-current application.

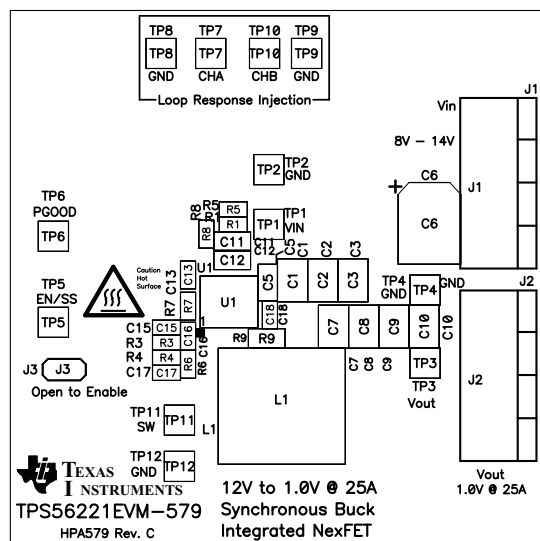


Figure 17. TPS56221EVM-579 Top Assembly Drawing (top view)

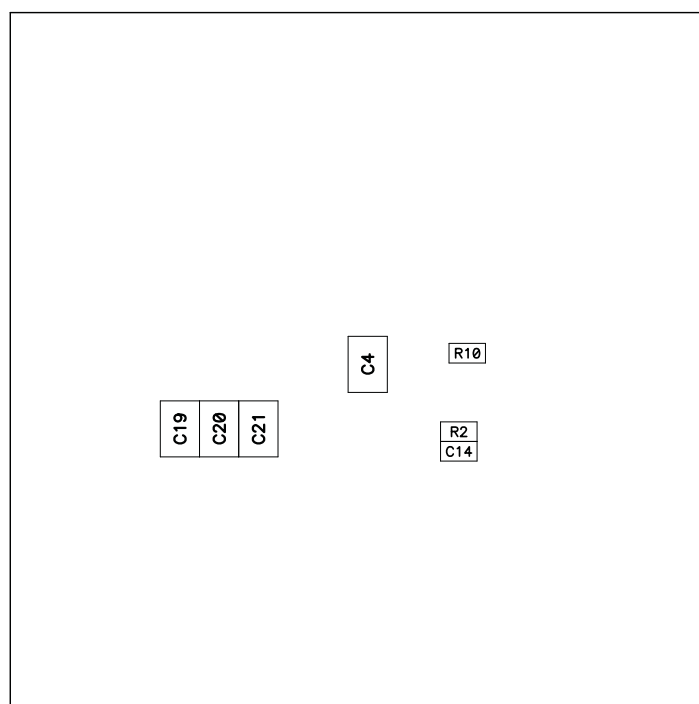


Figure 18. TPS56221EVM-579 Bottom Assembly Drawing (bottom view)

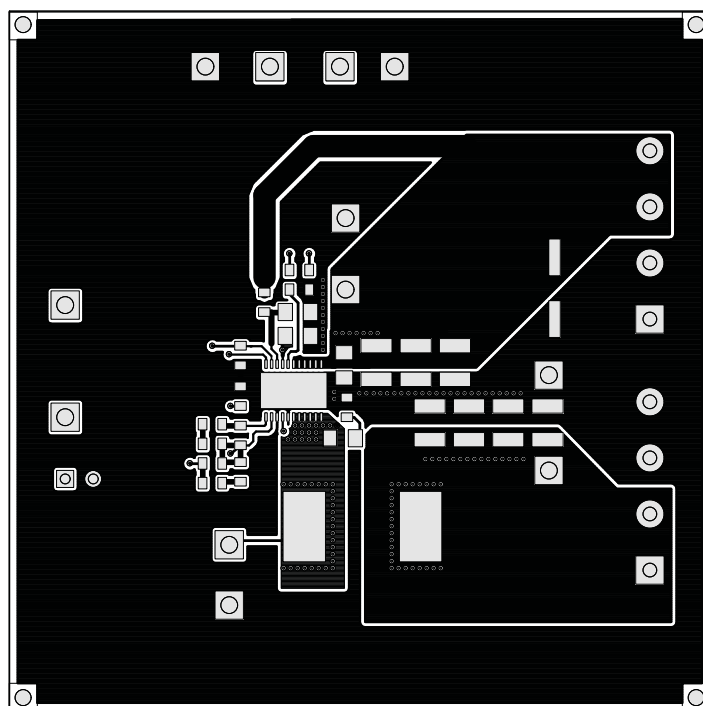


Figure 19. TPS56221EVM-579 Top Copper (top view)

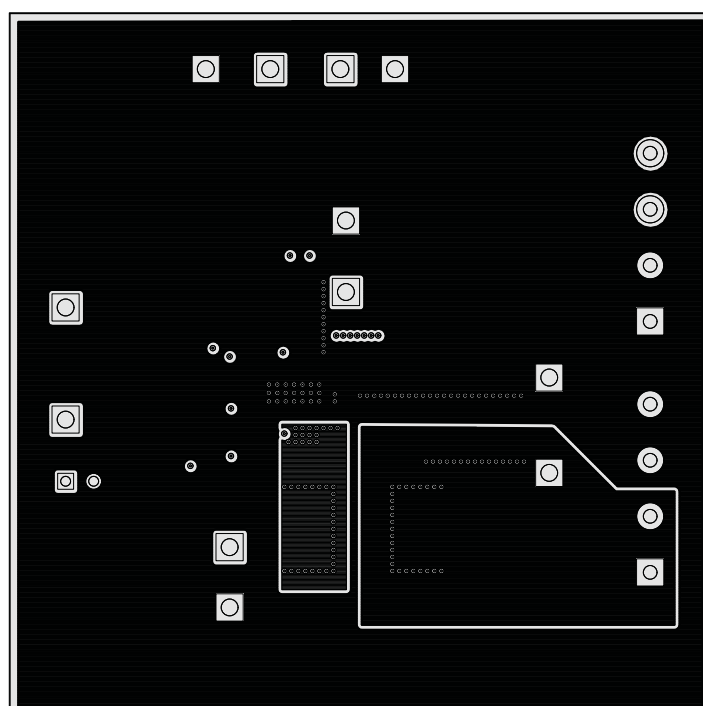


Figure 20. TPS56221EVM-579 Internal 1 (top view)

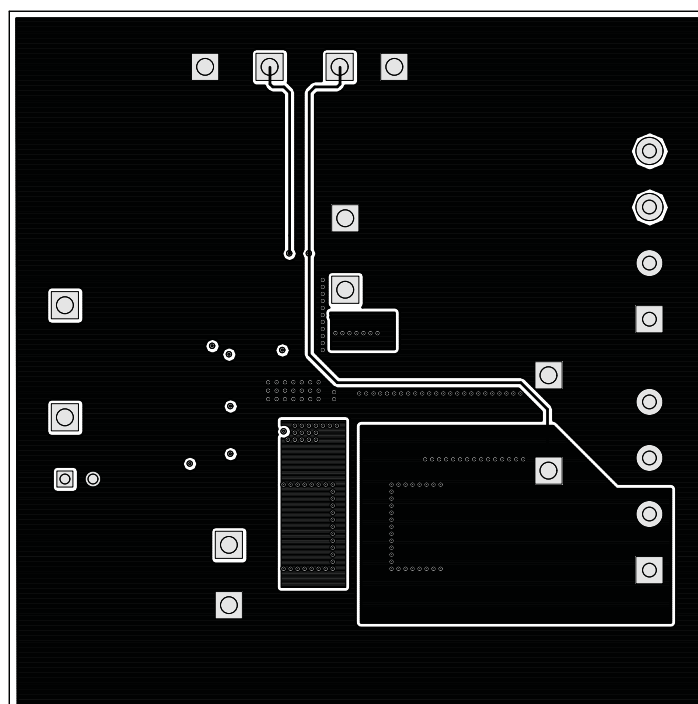


Figure 21. TPS56221EVM-579 Internal 2 (top view)

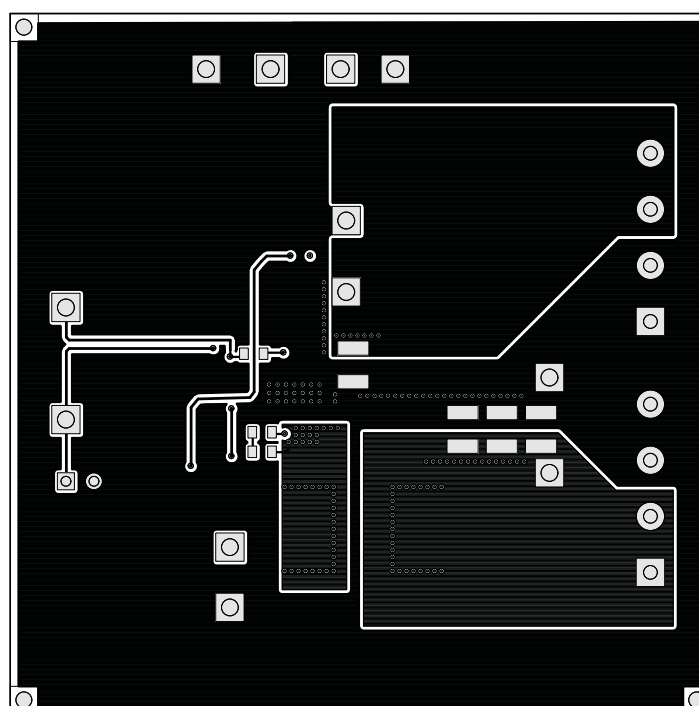


Figure 22. TPS56221EVM-579 Bottom Copper (top view)

11 List of Materials

Table 3. TPS56221EVM-579 List of Materials

QTY	REF DES	DESCRIPTION	PART NUMBER	MFR
4	C1, C2, C3, C4	Capacitor, ceramic, 25 V, X5R, 20%, 22 μ F, 1210	Std	Std
2	C5, C11	Capacitor, ceramic, 25 V, X5R, 20%, 1.0 μ F, 0805	Std	Std
0	C6	Capacitor, aluminum, 16 V _{DC} , $\pm$ 20%, 100 μ F, code D8	EEEF1C101AP	Panasonic
5	C7, C8, C9, C10, C19	Capacitor, ceramic, 6.3 V, X5R, 20%, 100 μ F, 1210	Std	Std
1	C12	Capacitor, ceramic, 10 V, X5R, 20%, 4.7 μ F, 0805	Std	Std
1	C13	Capacitor, ceramic, 16 V, X7R, 20%, 33 nF, 0603	Std	Std
1	C14	Capacitor, ceramic, 50 V, X7R, 20%, 100 nF, 0603	Std	Std
2	C15, C18	Capacitor, ceramic, 50 V, X7R, 10%, 2200 pF, 0603	Std	Std
1	C16	Capacitor, ceramic, 50 V, C0G, 5%, 100 pF, 0603	Std	Std
1	C17	Capacitor, ceramic, 50 V, C0G, 5%, 680 pF, 0603	Std	Std
0	C20, C21	Capacitor, ceramic, 6.3 V, X5R, 20%, 100 μ F, 1210	Std	Std
2	J1, J2	Terminal block, 4 pin, 15 A, 5.1 mm, 0.80 inch x 0.35 inch	ED120/4DS	OST
1	J3	Header, male 2 pin, 100-mil spacing, 0.100 inch x 2 inch	PEC02SAAN	Sullins
1	L1	Inductor, 0.32 m Ω , 320 nH, 0.530 inch x 0.510 inch	PA0513.321NLT	Pulse
1	R1	Resistor, chip, 1/16 W, 1%, 2.87 k Ω , 0603	Std	Std
1	R2	Resistor, chip, 1/16 W, 1%, 5.10 Ω , 0603	Std	Std
1	R3	Resistor, chip, 1/16 W, 1%, 7.87 k Ω , 0603	Std	Std
1	R4	Resistor, chip, 1/16 W, 1%, 20.5 k Ω , 0603	Std	Std
1	R5	Resistor, chip, 1/16 W, 1%, 49.9 Ω , 0603	Std	Std
1	R6	Resistor, chip, 1/16 W, 1%, 1.00 k Ω , 0603	Std	Std
1	R7	Resistor, chip, 1/16 W, 1%, 30.1 k Ω , 0603	Std	Std
1	R8	Resistor, chip, 1/16 W, 1%, 0 k Ω , 0603	Std	Std
1	R9	Resistor, chip, 1/8 W, 1%, 1.00 Ω , 0805	Std	Std
1	R10	Resistor, chip, 1/16 W, 1%, 100 k Ω , 0603	Std	Std
3	TP1, TP3, TP11	Test point, red, thru hole, 0.125 inch x 0.125 inch	5010	Keystone
5	TP2, TP4, TP8, TP9, TP12	Test point, black, thru hole, 0.125 inch x 0.125 inch	5011	Keystone
2	TP5, TP6	Test point, yellow, thru hole, 0.125 x 0.125 inch	5014	Keystone
2	TP7, TP10	Test point, white, thru hole, 0.125 x 0.125 inch	5012	Keystone
1	U1	4.5-V to 14-V Input 25-A Synchronous Buck Converter, QFN-22 6 mm x 5 mm	TPS56221DQP	TI
1	--	PCB, 2.5 inch x 2.5 inch x 0.062 inch	HPA579	Any
1	--	Shunt, 100 mil, black, 0.100	929950-00	3M

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EVM Warnings and Restrictions

It is important to operate this EVM within the input voltage range of 8 VDC to 14 VDC and the output voltage range of 0 ADC to 25 ADC.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 85°C. The EVM is designed to operate properly with certain components above 85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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